

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A semiconductor manufacturing apparatus, comprising:
a wafer support that has a tapered lateral side that supports an edge of a wafer from below said wafer;
a stage on which said wafer is placed; and
wafer clamps that come into contact with ~~[[the]]~~ a perimeter of said wafer from above said wafer.

Claim 2 (Original): The semiconductor manufacturing apparatus according to claim 1, further comprising a holder that accommodates said wafer clamps.

Claim 3 (Original): The semiconductor manufacturing apparatus according to claim 2, wherein said holder is tubular.

Claim 4 (Currently Amended): The semiconductor manufacturing apparatus according to claim 2, wherein said wafer clamps are attached to said holder by ~~a screw~~ screws.

Claim 5 (Original): The semiconductor manufacturing apparatus according to claim 2, further comprising a seat that accommodates said holder.

Claim 6 (Original): The semiconductor manufacturing apparatus according to claim 5, wherein said seat is tubular.

Claim 7 (Original): The semiconductor manufacturing apparatus according to claim 5, wherein said holder is attached to said seat by a screw.

Claim 8 (Currently Amended): The semiconductor manufacturing apparatus according to claim 5, wherein male threads are formed at an ~~in the~~ outside surface of said holder and female threads that mesh with said male threads are formed at an inside surface of said seat.

Claim 9 (Currently Amended): The semiconductor manufacturing apparatus according to claim 1, wherein said wafer is placed on said stage ~~[[by]]~~ whereby said stage ~~supporting~~ supports a center portion of said wafer from below said wafer.

Claim 10 (Original): The semiconductor manufacturing apparatus according to claim 1, wherein said stage is an electrode.

Claim 11 (Original): The semiconductor manufacturing apparatus according to claim 1, wherein said stage accommodates a chuck for placing said wafer on said stage.

Claim 12 (Original): The semiconductor manufacturing apparatus according to claim 11, wherein said stage is of a cylindrical shape having a hollow portion and accommodates said chuck in said hollow portion.

Claim 13 (Currently Amended): In a semiconductor manufacturing apparatus having a wafer support that has a tapered lateral side that supports an edge of a wafer from below said wafer; wafer clamps that come into contact with ~~[[the]]~~ a perimeter of said wafer from above said wafer; and a stage that supports said wafer on an upper surface thereof,

a positioning jig, that is to be employed for positioning said wafer clamps,
comprising comprises:

a recess that fits onto said stage so as to cover said stage ~~[[same]]~~; and
a lateral side that, in a state in which said recess is fitted onto said stage, comes into contact with said wafer clamps, thereby specifying ~~[[the]]~~ a position of said wafer clamps.

Claim 14 (Original): The positioning jig according to claim 13, wherein said lateral side is perpendicular to said upper surface of said stage when said recess is fitted onto said stage.

Claim 15 (Original): The positioning jig according to claim 13, wherein said positioning jig is of a cylindrical or prismatic shape that has said recess in a bottom side thereof.

Claim 16 (Currently Amended): The positioning jig according to claim 13, comprising:
an upper structure of a cylindrical or prismatic shape; and
a lower structure that has a cylindrical or prismatic shape and whose upper and bottom sides are wider than ~~[[the]]~~ a bottom side of said upper structure;
wherein said recess is formed in the bottom side of said lower structure.

Claim 17 (Currently Amended): A wafer-securing method, comprising:
disposing a stage that has an upper surface~~[[, and]] on whose said upper surface~~
which a wafer is to be placed~~[[;]]~~, and a wafer support that has a tapered lateral side that supports an edge of said wafer from below said wafer;
placing said wafer on said stage and determining ~~[[the]]~~ a position at which said wafer is to be placed by said edge of said wafer coming into contact with said lateral side; and

securing said wafer by using wafer clamps that come into contact with ~~[[the]]~~ a perimeter of said wafer from above said wafer.

Claim 18 (Currently Amended): The wafer-securing method according to claim 17, further comprising attaching ~~a step in which~~ said wafer clamps to an ~~are attached~~ inside ~~[[the]]~~ surface of a holder.

Claim 19 (Currently Amended): The wafer-securing method according to claim 18, wherein~~[[, as]]~~ said holder~~[[,]]~~ a holder ~~is~~ of a tubular shape ~~is selected~~.

Claim 20 (Currently Amended): The wafer-securing method according to claim 18, wherein~~[[,]]~~ said wafer clamps are attached to said holder by screws ~~a screw~~.

Claim 21 (Currently Amended): The wafer-securing method according to claim 18, further comprising attaching ~~a step in which~~ said holder ~~is attached to an~~ inside ~~[[the]]~~ surface of a seat.

Claim 22 (Original): The wafer-securing method according to claim 21, wherein a tubular shape is selected for said seat.

Claim 23 (Original): The wafer-securing method according to claim 21, wherein said holder is attached to said seat by a screw.

Claim 24 (Currently Amended): The wafer-securing method according to claim 21, wherein[[, as]] said holder[[,]] ~~a holder is selected that~~ has male threads formed in an [[the]] outside surface thereof[[,]], and[[, as]] said seat[[,]] ~~a seat is selected that~~ has female threads formed in the inside surface thereof that mesh with said male threads.

Claim 25 (Currently Amended): [[The]] A wafer-securing method ~~according to claim~~ 17[[,]] further comprising:

disposing a stage that has an upper surface on which a wafer is to be placed,
and a wafer support that has a tapered lateral side that supports an edge of said wafer
from below said wafer;

placing said wafer on said stage and determining a position at which said wafer
is to be placed by said edge of said wafer coming into contact with said lateral side;

securing said wafer by using wafer clamps that come into contact with a
perimeter of said wafer from above said wafer;

fitting a positioning jig, that has a lateral side and a recess that is fitted fittable
onto said stage, onto said stage so as to cover said stage [[same]]; and

positioning said wafer clamps by bringing said wafer clamps into contact with
said lateral side of said jig.

Claim 26 (Currently Amended): The wafer-securing method according to claim 25, wherein[[, as]] said jig[[,.]] ~~a jig is selected whose~~ has a lateral side that is perpendicular to said upper surface of said stage when said recess is fitted onto said stage.

Claim 27 (Currently Amended): The wafer-securing method according to claim 25, wherein[[, as]] said jig[[,.]] ~~a jig is selected that is of~~ has a cylindrical or prismatic shape that has said recess in a bottom side thereof.

Claim 28 (Currently Amended): The wafer-securing method according to claim 25, wherein[[, as]] said jig[[,.]] ~~a jig is selected that~~ comprises:

an upper structure of a cylindrical or prismatic shape; and

a lower structure that has a cylindrical or prismatic shape and [[whose]] which has upper and bottom sides that are wider than [[the]] a bottom side of said upper structure[[;]].

wherein ~~and that has~~ said recess is formed in the bottom side of said lower structure.